

Amendments To The Claims:

Please amend the claims as follows:

1. (*Currently amended*) A polishing composition used in a polishing process for reducing haze level of wafer surface, comprising:

hydroxyethyl cellulose compounded in said composition in a quantity larger than ~~0.01%~~ 0.05% by weight and smaller than ~~3%~~ 2% by weight and having an average molecular weight in the range of 300,000 to ~~3,000,000~~ 2,000,000;

polyethylene oxide compounded in said composition in a quantity larger than 0.005% by weight and smaller than 0.5% by weight and having an average molecular weight in the range of ~~30,000 to 50,000,000~~ 50,000 to 10,000,000;

~~an alkaline compound~~ ammonia compounded in said composition in a quantity larger than 0.02% by weight and smaller than 4% by weight;

water; and

silicon dioxide.

2. (*Original*) The polishing composition according to claim 1, wherein the total content of iron, nickel, copper, and calcium in the silicon dioxide, as measured in a 20 wt-% aqueous solution of said silicon dioxide, is 300 ppm or less.

3. (*Original*) The polishing composition according to claim 1, wherein the content of hydroxyethyl cellulose in the polishing composition is 0.1 to 1% by weight.

4. (*Original*) The polishing composition according to claim 1, wherein the content of silicon dioxide in the polishing composition is 3 to 20% by weight.

5. (*Canceled*)

6. (*New*) The polishing composition according to claim 1, wherein the content of hydroxyethyl cellulose in the polishing composition is 0.1 to 1% by weight.

7. (New) The polishing composition according to claim 1, wherein the average molecular weight of hydroxyethyl cellulose in the polishing composition is 600,000 to 2,000,000.

8. (New) The polishing composition according to claim 1, wherein the average molecular weight of hydroxyethyl cellulose in the polishing composition is 900,000 to 1,500,000.

9. (New) The polishing composition according to claim 1, wherein the content of polyethylene oxide in the polishing composition is 0.01 to 0.4% by weight.

10. (New) The polishing composition according to claim 1, wherein the content of polyethylene oxide in the polishing composition is 0.03 to 0.2% by weight.

11. (New) The polishing composition according to claim 1, wherein the average molecular weight of polyethylene oxide in the polishing composition is 100,000 to 1,000,000.

12. (New) The polishing composition according to claim 1, wherein the content of ammonia in the polishing composition is 0.03 to 3% by weight.

13. (New) The polishing composition according to claim 1, wherein the content of ammonia in the polishing composition is 0.2 to 2% by weight.